

10/031, 983

WEST Search History

DATE: Thursday, May 15, 2003

Set Name Query
side by side

Hit Count Set Name
result set

DB=USPT,PGPB; PLUR=YES; OP=ADJ

L9	12 near7 (13 or 14 or 15 or 16)	77	L9
L8	12 near7 (13 or 14 or 15 or 16)	77	L8

DB=JPAB,EPAB,DWPI,TDBD; PLUR=YES; OP=ADJ

(thiirane or episulfide or episulphide or epithio\$ or dithiirane or polythiirane or diepisulfide or diepisulphide or polyepisulfide or polyepisulphide or diepithio\$ or polyepithio\$) and ((amin?\$\$1 or diamin?\$\$1 or polyamin?\$\$! or butylamine or octylamine or cyclohexylamine or benzylamine or methylbutylamine) or (diaminopropane or propanediamine or

L7	propylenediamine or diaminocyclohexane or cyclohexanediamine or aminoethylpiperazine or (aminoethyl adj piperazine)) or (diethylenetriamine or triamine or isophoronediamine or xylylenediamine or (diamin? adj3 methylpentane) or methylpentanediamine) or (aminomethylnorbornane or (aminomethyl adj norbornane) or ethylenediamine))	144	L7
----	--	-----	----

DB=USPT,PGPB; PLUR=YES; OP=ADJ

L6	aminomethylnorbornane or (aminomethyl adj norbornane) or ethylenediamine	40569	L6
----	--	-------	----

L5	diethylenetriamine or triamine or isophoronediamine or xylylenediamine or (diamin? adj3 methylpentane) or methylpentanediamine	25588	L5
----	--	-------	----

L4	diaminopropane or propanediamine or propylenediamine or diaminocyclohexane or cyclohexanediamine or aminoethylpiperazine or (aminoethyl adj piperazine)	15591	L4
----	---	-------	----

L3	amin?\$\$1 or diamin?\$\$1 or polyamin?\$\$! or butylamine or octylamine or cyclohexylamine or benzylamine or methylbutylamine	392132	L3
----	--	--------	----

L2	thiirane or episulfide or episulphide or epithio\$ or dithiirane or polythiirane or diepisulfide or diepisulphide or polyepisulfide or polyepisulphide or diepithio\$ or polyepithio\$	1013	L2
----	--	------	----

POLYGRAPH

DB=DWPI; PLUR=YES; OP=ADJ

L1 ep-449776-\$.did.

1 L1

END OF SEARCH HISTORY

WEST

End of Result Set

 Generate Collection

L1: Entry 1 of 1

File: DWPI

Sep 3, 2002

DERWENT-ACC-NO: 1991-290167

DERWENT-WEEK: 200266

COPYRIGHT 2003 DERWENT INFORMATION LTD

TITLE: Epoxy! resin with improved fracture toughness - contg. epoxy! resin, anhydride hardener, impact modifier and a cpd. with 2 active hydrogen atoms

INVENTOR: ELDIN, S H; MAURER, J ; PEYER, R P ; GRIESHABER, P ; RIME, F

PATENT-ASSIGNEE:

ASSIGNEE	CODE
CIBA GEIGY AG	CIBA
VANTICO AG	VANTN
CIBA SC HOLDING AG	CIBA
CIBA SPECIALTY CHEM HOLDING INC	CIBA
CIBA SPECIALTY CHEM CORP	CIBA

PRIORITY-DATA: 1990CH-0001055 (March 30, 1990)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
CA 2039404 C	September 3, 2002	E	000	C08L051/04
<u>EP 449776 A</u>	October 2, 1991		000	
AU 9173970 A	October 3, 1991		000	
CA 2039404 A	October 1, 1991		000	
ZA 9102361 A	December 24, 1991		000	
AU 638816 B	July 8, 1993		000	C08G059/58
<u>EP 449776 A3</u>	September 23, 1992		000	
JP 06049179 A	February 22, 1994		012	C08G059/42
US 5789482 A	August 4, 1998		000	C08L063/00
KR 193147 B1	June 15, 1999		000	C08L063/00
JP 3300955 B2	July 8, 2002		012	C08G059/42

DESIGNATED-STATES: CH DE ES FR GB IT LI NL SE

CITED-DOCUMENTS: NoSR.Pub; EP 191872 ; EP 245018 ; US 3856883

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	descriptor
CA 2039404C	March 28, 1991	1991CA-2039404	
EP 449776A	March 21, 1991	1991EP-0810191	
ZA 9102361A	March 28, 1991	1991ZA-0002361	
AU 638816B	March 28, 1991	1991AU-0073970	
AU 638816B		AU 9173970	Previous Publ.
EP 449776A3	March 21, 1991	1991EP-0810191	
JP 06049179A	March 29, 1991	1991JP-0091759	
US 5789482A	March 25, 1991	1991US-0674637	CIP of
US 5789482A	September 28, 1992	1992US-0952122	
KR 193147B1	March 20, 1991	1991KR-0004364	
JP 3300955B2	March 29, 1991	1991JP-0091759	
JP 3300955B2		JP 6049179	Previous Publ.

INT-CL (IPC): B32B 27/38; C08G 59/40; C08G 59/42; C08G 59/58; C08G 59/62; C08J 0/00; C08K 0/00; C08L 21/00; C08L 51/00; C08L 51/04; C08L 63/00; C08L 63/02; C08L 63/04

ABSTRACTED-PUB-NO: EP 449776A

BASIC-ABSTRACT:

Epoxy resinm compsns. (I) are claimed, contg, (a) epoxy resin(s) with more than one 1,2-epoxide gp./mol. on average, (b) anhydride hardener, (c) impact modifier, and (d) a cpd. with 2 active H atoms which can react with (a).

(I) also contain a fillers, (a) is based on Bisphenol A or F or on a cyclo-olefin, has 2 epoxide gps./mol. and is a low-viscosity liq. (b) is a linear aliphatic polymeric anhydride or (pref.) a cyclic carboxylic acid anhydride. (I) also contains an accelerator for (b). (c) is a core/shell polymer, pref. with no gps. in the shell which react with epoxide gps., pref. with particle size 0.05-30 microns and pref. with a core contg. polybutadiene.

USE/ADVANTAGE - (I) are useful as casting resins, laminating resins, moulding resins, coating materials or encapsulating resins for electrical or electronic components (claimed). Also claimed are cured prods. obtd. by hardening (I) by conventional methods.

ABSTRACTED-PUB-NO:

US 5789482A

EQUIVALENT-ABSTRACTS:

Epoxy resinm compsns. (I) are claimed, contg, (a) epoxy resin(s) with more than one 1,2-epoxide gp./mol. on average, (b) anhydride hardener, (c) impact modifier, and (d) a cpd. with 2 active H atoms which can react with (a).

(I) also contain a fillers, (a) is based on Bisphenol A or F or on a cyclo-olefin, has 2 epoxide gps./mol. and is a low-viscosity liq. (b) is a linear aliphatic polymeric anhydride or (pref.) a cyclic carboxylic acid anhydride. (I) also contains an accelerator for (b). (c) is a core/shell polymer, pref. with no gps. in the shell which react with epoxide gps., pref. with particle size 0.05-30 microns and pref. with a core contg. polybutadiene.

USE/ADVANTAGE - (I) are useful as casting resins, laminating resins, moulding resins, coating materials or encapsulating resins for electrical or electronic components (claimed). Also claimed are cured prods. obtd. by hardening (I) by conventional methods.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: POLYEPOXIDE RESIN IMPROVE FRACTURE TOUGH CONTAIN POLYEPOXIDE RESIN ANHYDRIDE HARDEN IMPACT MODIFIED COMPOUND ACTIVE HYDROGEN ATOM

DERWENT-CLASS: A21 A85 L03 P73 U11 V04

CPI-CODES: A05-A01B1; A08-D02; A08-M10; L03-H04E8; L03-J; L04-C20A;

WEST

 Generate Collection

L7: Entry 111 of 144

File: DWPI

Apr 15, 1977

DERWENT-ACC-NO: 1977-38194Y

DERWENT-WEEK: 197722

COPYRIGHT 2003 DERWENT INFORMATION LTD

TITLE: Storable liq. episulphide resins - from mixts. of epoxy resins and thiourea in solvent soln.

PATENT-ASSIGNEE:

ASSIGNEE	CODE
SIKA AG	SIKAN

PRIORITY-DATA: 1974CH-0002455 (February 21, 1974)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
CH 586732 A	April 15, 1977		000	

INT-CL (IPC): C07D 331/02; C08G 85/00; C08L 63/00; C08L 101/02

ABSTRACTED-PUB-NO: CH 586732A

BASIC-ABSTRACT:

Prepn. comprises reaction of a mixt. of epoxy resins in solvent with thiourea. Alternatively, different epoxy resins can be separately reacted and the episulphide resins obtd. can then be mixed.

Used as a component of hardenable resin compsns. partic. with polyamines- and as an accelerator for epoxy-polyamide resin mixts. used in the building industry. Prods. are practically odourless and have less tendency to gel than those obtd. using thiocyanates or Na thiosulphate.

In an example an episulphide resin prep'd. from 48 g Bisphenol A type epoxy resin (epoxy value 0.56), 50 g same type of epoxy value 0.22 and 2 g of aliphatic diglycidyl ether of epoxy value 0.70 had a storage stability of 4 months at 20 degrees C and only slight odour.

TITLE-TERMS: STORAGE LIQUID EPISULPHIDE RESIN MIXTURE EPOXY RESIN THIOUREA SOLVENT SOLUTION

DERWENT-CLASS: A26

CPI-CODES: A05-A01D; A05-J05; A08-D;

Multipunch Codes: 010 02& 040 05- 141 199 220 221 226 231 250 273 299 311 336 341 359 400 475 525 527 532 536 546
613 720 724

WEST

 Generate Collection

L7: Entry 75 of 144

File: DWPI

Jul 11, 1995

DERWENT-ACC-NO: 1995-272961

DERWENT-WEEK: 199536

COPYRIGHT 2003 DERWENT INFORMATION LTD

TITLE: Mfr. of modified polyamide-poly:amine(s) with excellent curative properties - comprises reacting thiirane cpd. and polyamide-poly:amine without formation of by=product sulphur cpds.

PATENT-ASSIGNEE:

ASSIGNEE	CODE
NIPPON SHOKUBAI CO LTD	JAPC

PRIORITY-DATA: 1993JP-0317979 (December 17, 1993)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 07173283 A	July 11, 1995		004	C08G073/02

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP 07173283A	December 17, 1993	1993JP-0317979	

INT-CL (IPC): C07 D 331/02; C08 G 69/48; C08 G 73/02

ABSTRACTED-PUB-NO: JP 07173283A

BASIC-ABSTRACT:

The mfr. of a modified polyamide-polyamine comprises reacting a thiirane cpd. of formula (I) and a polyamide-polyamine cpd. R1-4=H, alkyl or aromatic gp..

USE - Used as epoxy resin curatives, crosslinkers, vulcanisers, polymerisation regulators, antioxidants, metal-chelating agents and additives for lubricating oils.

ADVANTAGE - By-product S cpds. with offensive odour are not produced in mfr.. The modified polyamide-polyamines have highly reactive amino and mercapto gps. and excellent rapid and low temp. epoxy resin curative properties. Cured epoxy resins have improved corrosion resistance and excellent chemical, water and alkali resistance.

CHOSEN-DRAWING: Dwg.0/2

TITLE-TERMS: MANUFACTURE MODIFIED POLYAMIDE POLY AMINE CURE PROPERTIES COMPRISE REACT THIIRANE COMPOUND POLYAMIDE POLY AMINE FORMATION BY=PRODUCT SULPHUR COMPOUND

DERWENT-CLASS: A21 A23 A97 H07

CPI-CODES: A02-B; A05-A01B1; A05-F04; A08-A06; A08-A07; A08-C08; A08-D03; A08-D04; A10-E01; A12-W02A; H07-G;

WEST

 Generate Collection

L7: Entry 21 of 144

File: JPAB

Jul 11, 1995

PUB-NO: JP407173283A

DOCUMENT-IDENTIFIER: JP 07173283 A

TITLE: PRODUCTION OF MODIFIED POLYAMIDE-POLYAMINE

PUBN-DATE: July 11, 1995

INVENTOR-INFORMATION:

NAME

COUNTRY

KIMURA, KAZUMASA

KAI, TAKASHI

ASSIGNEE-INFORMATION:

NAME

COUNTRY

NIPPON SHOKUBAI CO LTD

APPL-NO: JP05317979

APPL-DATE: December 17, 1993

INT-CL (IPC): C08 G 73/02; C08 G 69/48; C07 D 331/02

ABSTRACT:

PURPOSE: To obtain a modified polyamide-polyamine having highly reactive amino and mercapto groups in the molecule and used as a curing agent for epoxy resin by reacting a polyamide-polyamine with a specified thiirane compound.

CONSTITUTION: A polyamide-polyamine compound is reacted with a thiirane compound of the formula (wherein R1, R2, R3 and R3 may be the same or different and are each H, alkyl or an aromatic group). Examples of the thiirane compound include ethylene sulfide, propylene sulfide, butylene sulfide and styrene sulfide. The polyamide-polyamine compound is obtained by the condensation of a polycarboxylic acid compound and a polyamine compound, an example thereof being a product of condensation of a polymeric fatty acid, such as a dimer or trimer acid, obtained by polymerizing a fatty acid having unsaturated bonds in the molecule with a polyamine compound, especially an aliphatic polyamine.

COPYRIGHT: (C)1995,JPO